

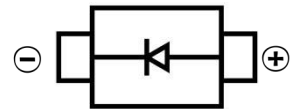
## SURFACE MOUNT SUPER FAST RECOVERY DIODES

### Features

- Glass Passivated Die Construction
- Ideally Suited for Automatic Assembly
- Low Forward Voltage Drop, High Efficiency
- Low Power Loss
- Super-Fast Recovery Time
- Plastic Case Material has UL Flammability Classification Rating 94V-O



SMC



### Mechanical Data

- Case: SMC/DO-214AB, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.21 grams (approx.)

### Maximum Ratings and Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	MURS305	MURS310	MURS315	MURS320	MURS330	MURS340	MURS360	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>								
Working Peak Reverse Voltage	V <sub>RWM</sub>	50	100	150	200	300	400	600	V
DC Blocking Voltage	V <sub>R</sub>								
RMS Reverse Voltage	V <sub>R(RMS)</sub>	35	70	105	140	210	280	420	V
Average Rectified Output Current @T <sub>L</sub> = 75°C	I <sub>O</sub>	3.0							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I <sub>FSM</sub>	100							A
Forward Voltage @I <sub>F</sub> = 3.0A	V <sub>FM</sub>	0.95				1.25		1.7	V
Peak Reverse Current @T <sub>A</sub> = 25°C	I <sub>RM</sub>	5.0							μA
At Rated DC Blocking Voltage @T <sub>A</sub> = 100°C		500							
Reverse Recovery Time (Note 1)	t <sub>rr</sub>	35							nS
Typical Junction Capacitance (Note 2)	C <sub>j</sub>	45							pF
Typical Thermal Resistance (Note 3)	R <sub>θJL</sub>	16							°C/W
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-65 to +150							°C

- Note: 1. Measured with I<sub>F</sub> = 0.5A, I<sub>R</sub> = 1.0A, I<sub>rr</sub> = 0.25A. See figure 5.  
 2. Measured at 1.0 MHz and applied reverse voltage of 4.0 V DC.  
 3. Mounted on P.C. Board with 8.0mm<sup>2</sup> land area.

**Typical Characteristics**

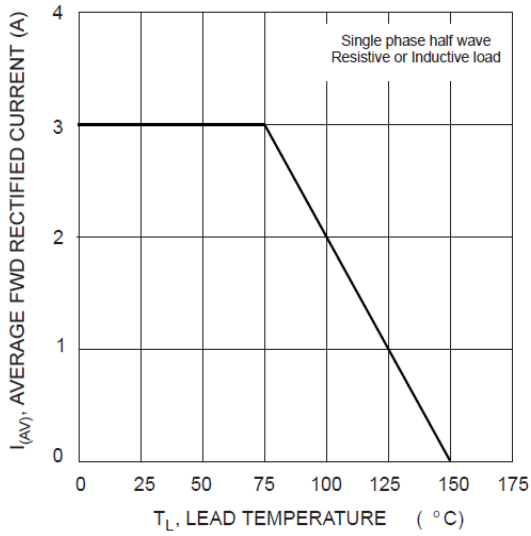


Fig. 1 Forward Current Derating Curve

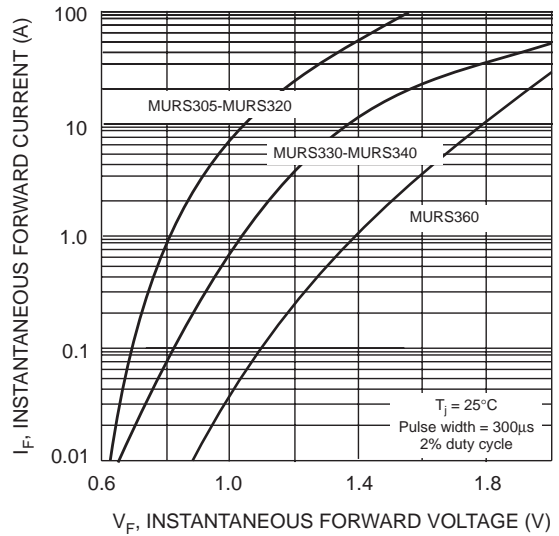


Fig. 2 Typical Forward Characteristics

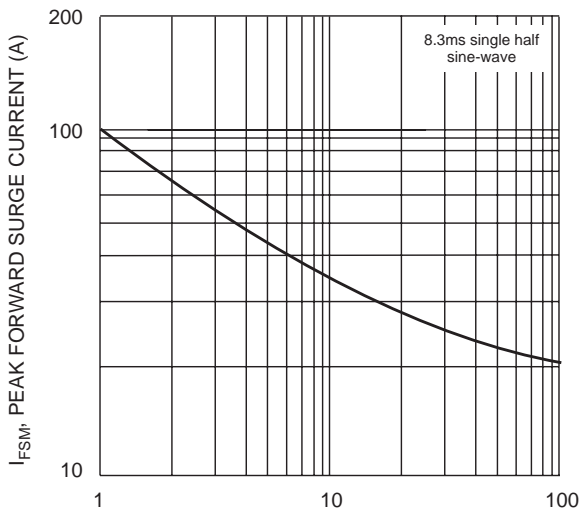


Fig. 3 Peak Forward Surge Current

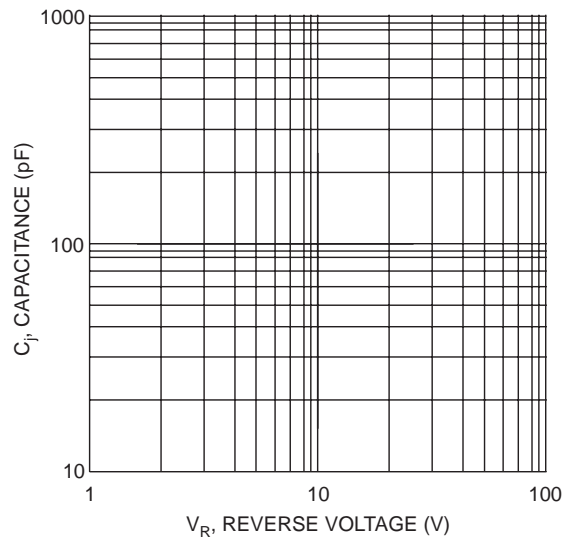
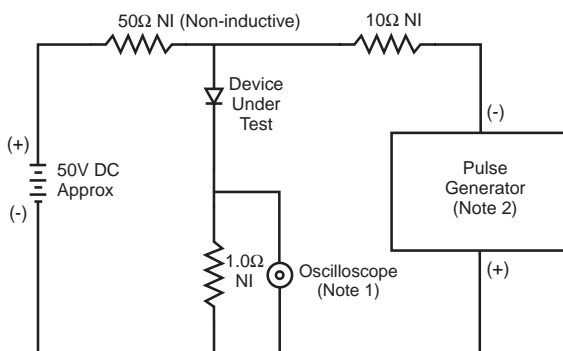
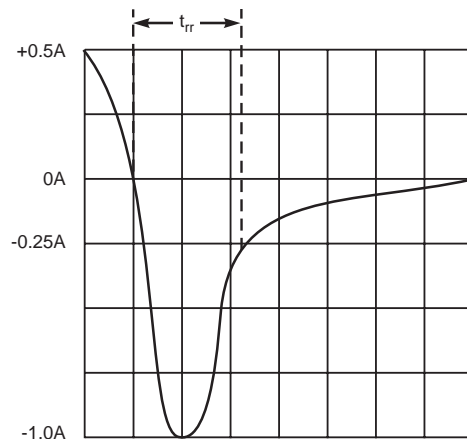


Fig. 4 Typical Junction Capacitance



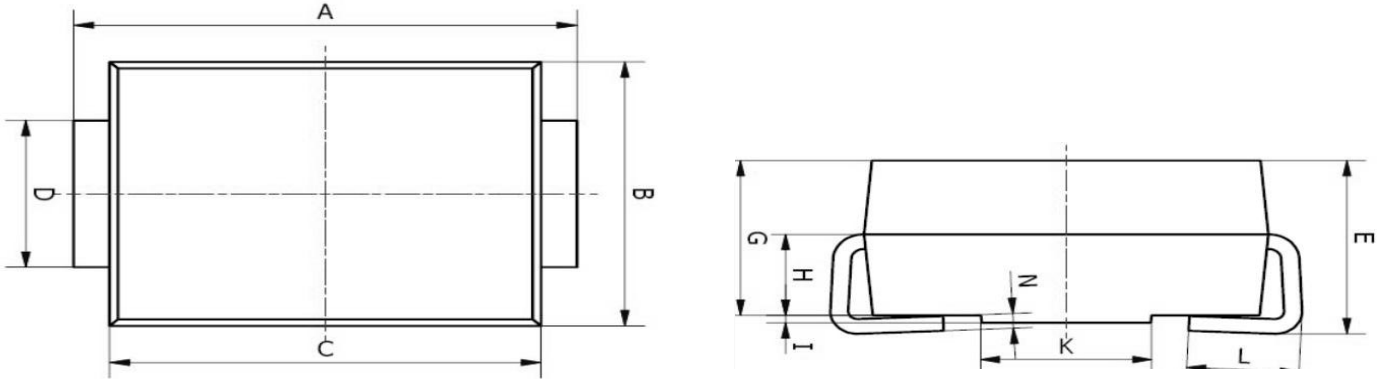
- Notes:  
 1. Rise Time = 7.0ns max. Input Impedance = 1.0M $\Omega$ , 22pF.  
 2. Rise Time = 10ns max. Input Impedance = 50 $\Omega$ .



Set time base for 5/10ns/cm

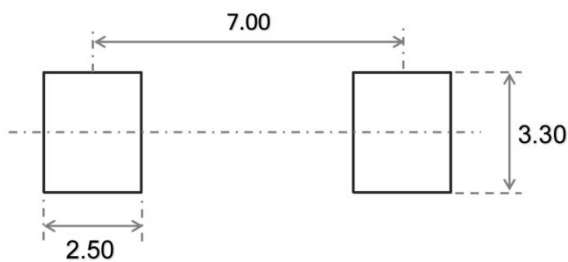
Fig. 5 Reverse Recovery Time Characteristic and Test Circuit

## SMC Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	7.75	8.13	0.305	0.320
B	5.59	6.22	0.220	0.245
C	6.60	7.11	0.260	0.280
D	2.75	3.25	0.108	0.128
E	2.25	2.82	0.089	0.111
G	2.00	2.62	0.079	0.103
H	1.26	1.56	0.050	0.061
I	0.05	0.15	0.002	0.006
K	4.30	6.00	0.169	0.236
L	1.25	1.75	0.049	0.069
N	0.10	0.30	0.004	0.012

## SMC Suggested Pad Layout

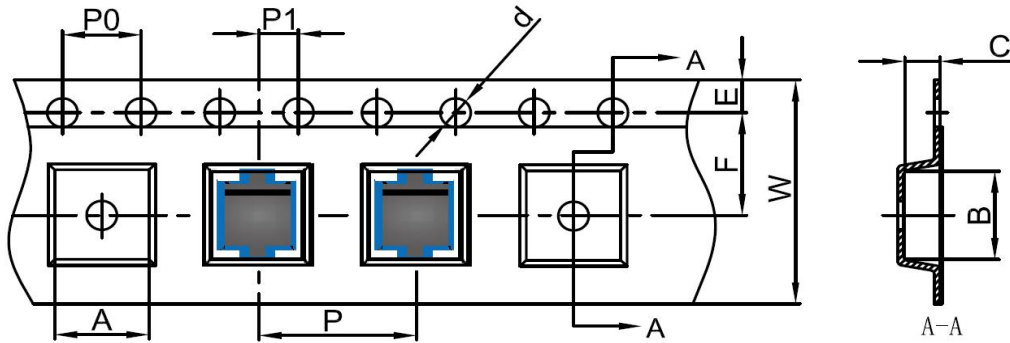


### Note:

1. Controlling dimension: in millimeters
2. General tolerance:  $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

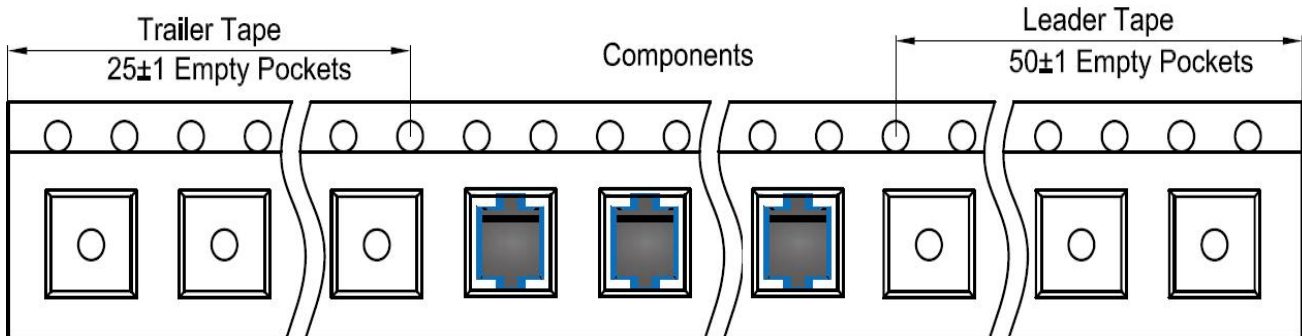
## SMC Tape and Reel

### SMC Embossed Carrier Tape

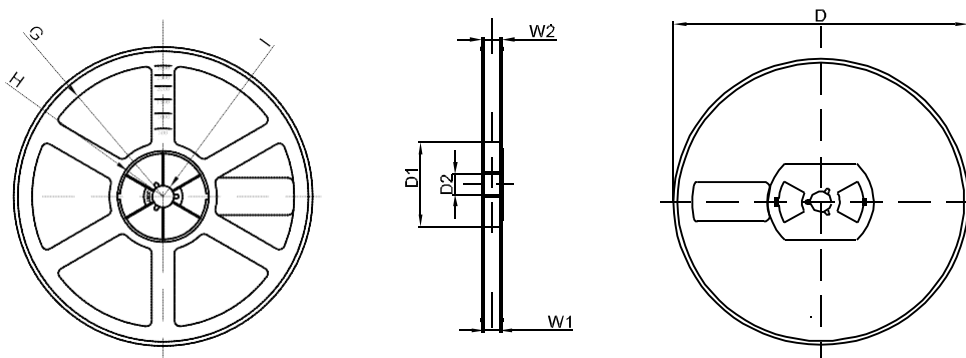


DIMENSIONS ARE IN MILLIMETER										
TYPE	A	B	C	d	E	F	P0	P	P1	W
SMC	6.3	8.25	2.90	Ø1.55	1.75	7.50	4.00	8.00	2.00	16.00
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

### SMC Tape Leader and Trailer



### SMC Reel



DIMENSIONS ARE IN MILLIMETER								
REEL OPTION	D	D1	D2	G	H	I	W1	W2
13" DIA	Ø330	100	21	R165	R50	R6.50	16.4	21.00
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1